Session Program

6-10 Sept 2010

Pixel2010 - International Workshop on Semiconductor Pixel Detectors for Particles and Imaging

X-Ray Imaging Applications

Grindelwald, Switzerland

Tuesday 7 September

Pixel detector for present and future experiments in synchrotron sources Speaker C. Schulze-Briese 09:30-09:50 EIGER: Next generation single photon counting detector for X-Ray applications Speaker R. Dinapoli 09:50-10:10 Energy-resolved X-Ray imaging method with the counting-type pixel detector Speaker H. Toyokawa 10:10-10:30 Development of CdTe Pixel Detector with Window Comparator ASIC for High Energy X-Ray Application Speaker T. Hirono 10:30-11:00 Coffee 11:00-11:20 Development of Multi-Via (MVIA) pixel with signal-charge division to realize high effective 105 dynamic range for X-ray and Free-Electron laser applications Speaker T. Hatsui 11:20-11:40 Charge integration readout ASICs for X-ray free electron lasers Speaker A. Mozzanica 11:40-12:00 The DSSC: a Large Format X-ray Imager with mega-Frame Readout Capability for the European XFEL Speaker M. Forro 12:00-12:20 First X-ray Imaging Measurements at the new SLAC Free Electron Laser	09:00-09:3	30
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14:00-14:20

Performance of the Medipix and Timepix devices for the recognition of electrongamma radiation fields

Speaker

C. Teyssier

14:20-14:50 Calibrations and Corrections for Single Counting Pixel Detectors

Speaker

Ch. Broennimann

14:50